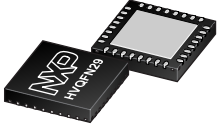


# SOT617-29

H-PQFN32, thermal enhanced - plastic quad flat non-lead, 32 terminals, no leads; 0.5 mm pitch, 5 mm x 5 mm x 0.9 mm body

2 April 2025

Package information



## 1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	H-PQFN32
Package style descriptive code	H-PQFN (thermal enhanced - plastic quad flat non-lead)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Manufacturer package code	98ASA02110D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	5	-	mm
package width	-	5	-	mm
package height	0.8	0.9	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	32	-	

H-PQFN32, thermal enhanced - plastic quad flat non-lead, 32 terminals, no leads; 0.5 mm pitch, 5 mm x 5 mm x 0.9 mm body

2 Package outline

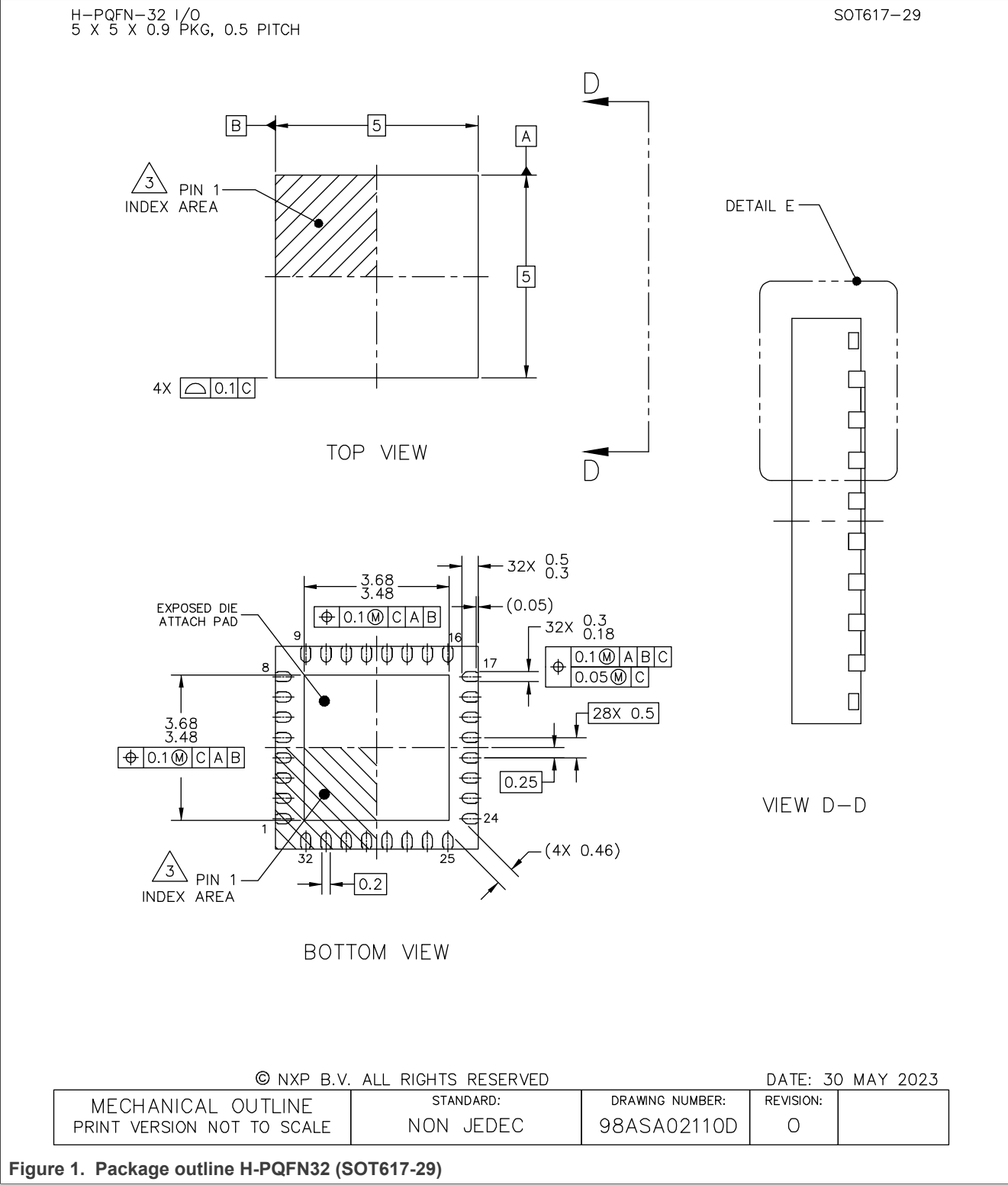
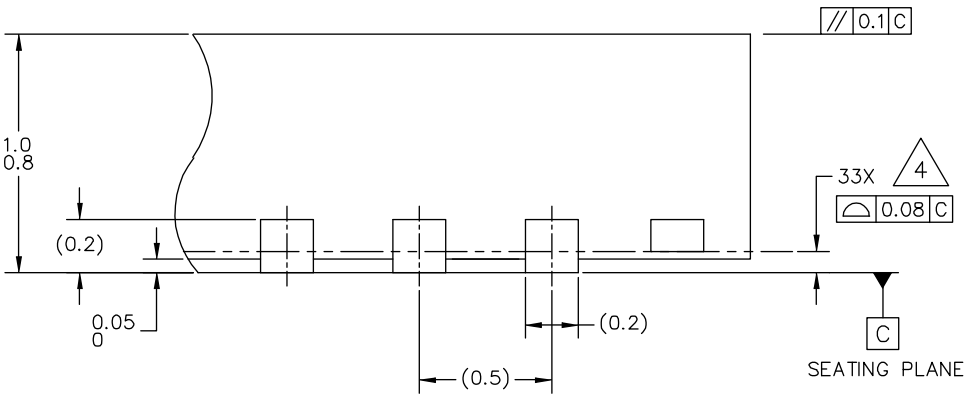


Figure 1. Package outline H-PQFN32 (SOT617-29)

H-PQFN32, thermal enhanced - plastic quad flat non-lead, 32 terminals, no leads; 0.5 mm pitch, 5 mm x 5 mm x 0.9 mm body

H-PQFN-32 I/O  
5 X 5 X 0.9 PKG, 0.5 PITCH

SOT617-29



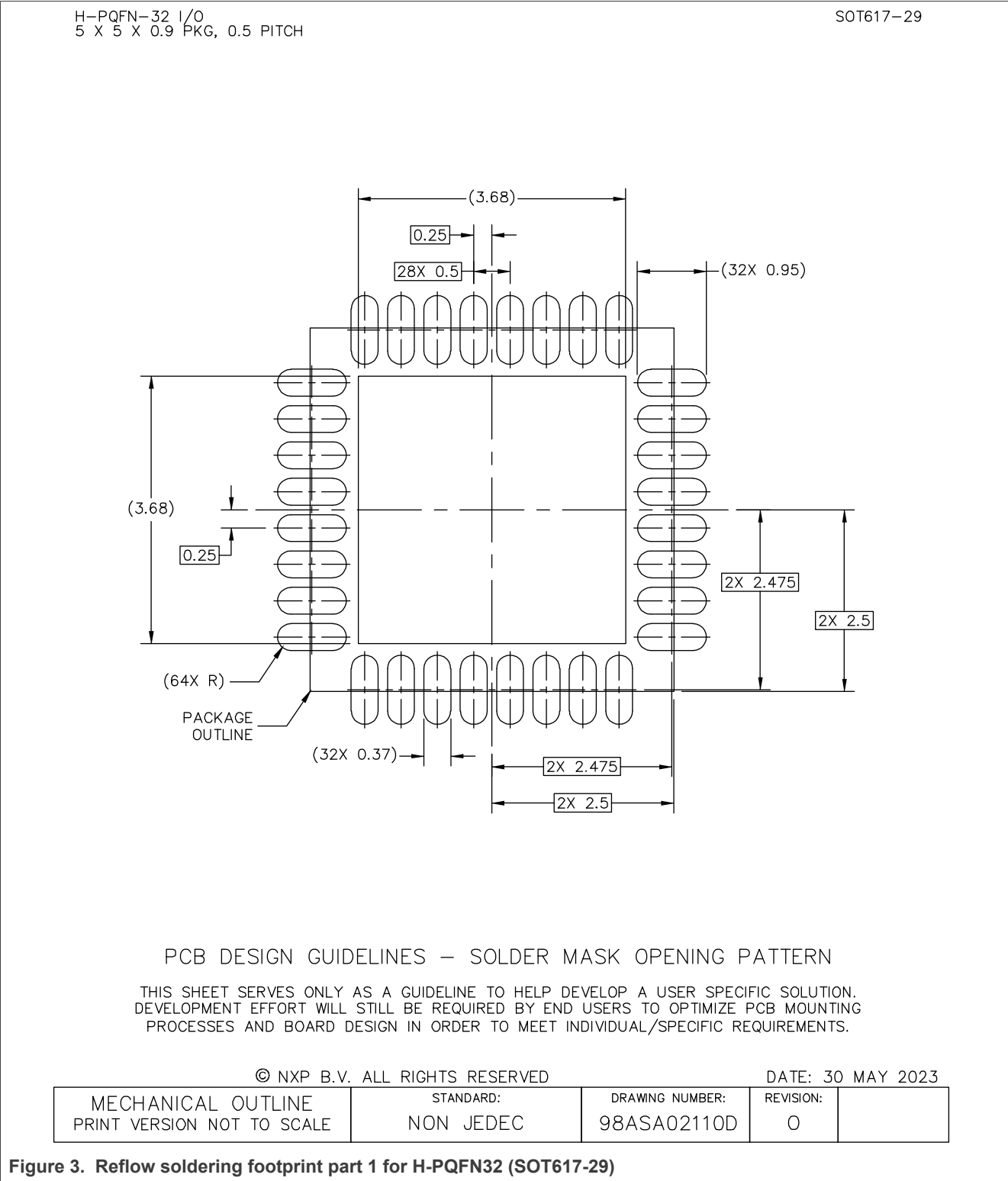
DETAIL E  
VIEW ROTATED 90° CW

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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA02110D	REVISION: O

Figure 2. Package outline detail E of H-PQFN32 (SOT617-29)

H-PQFN32, thermal enhanced - plastic quad flat non-lead, 32 terminals, no leads; 0.5 mm pitch, 5 mm x 5 mm x 0.9 mm body

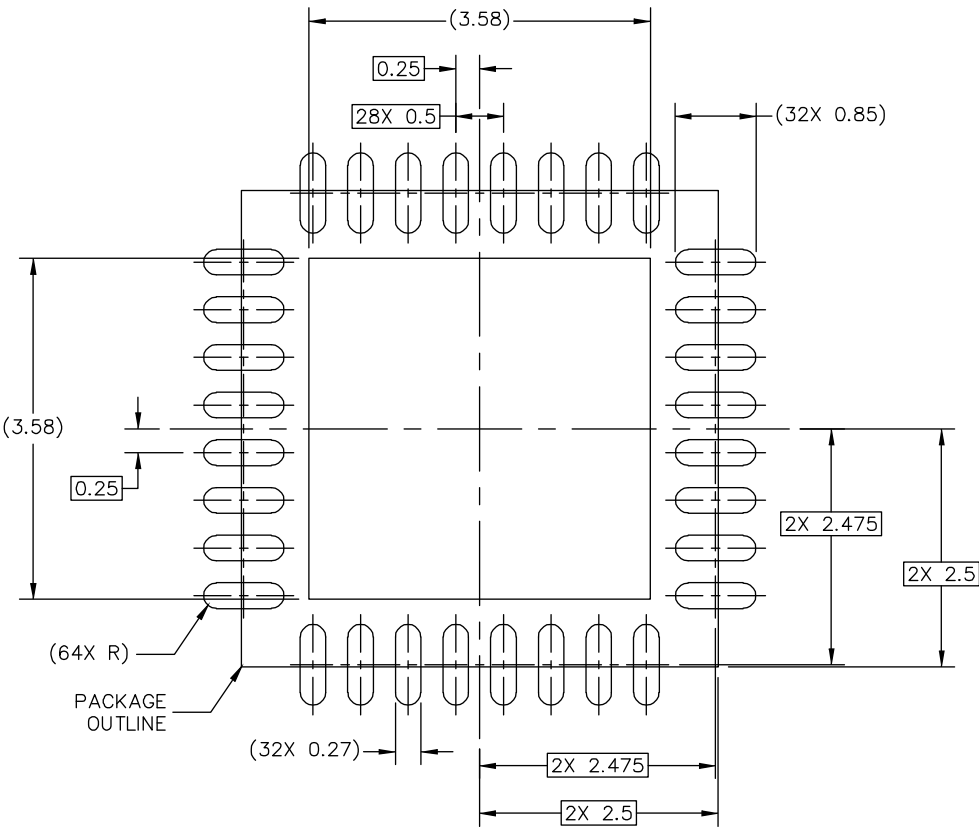
3 Soldering



H-PQFN32, thermal enhanced - plastic quad flat non-lead, 32 terminals, no leads; 0.5 mm pitch, 5 mm x 5 mm x 0.9 mm body

H-PQFN-32 I/O  
5 X 5 X 0.9 PKG, 0.5 PITCH

SOT617-29



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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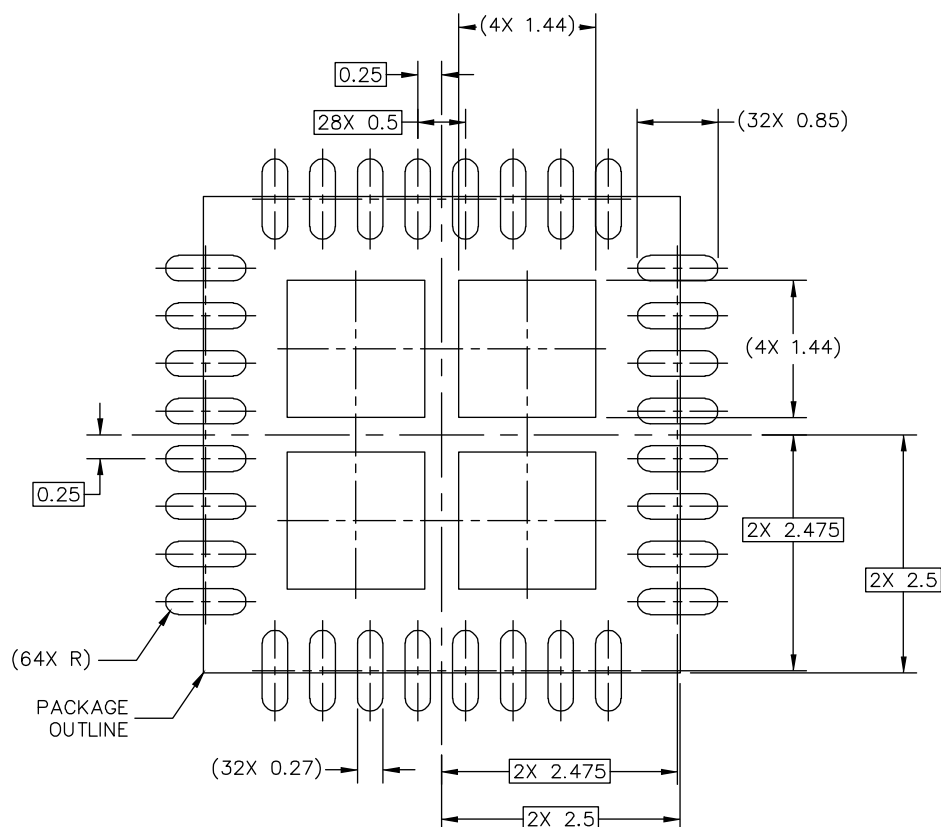
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA02110D	REVISION: O	
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Figure 4. Reflow soldering footprint part 2 for H-PQFN32 (SOT617-29)

**H-PQFN32, thermal enhanced - plastic quad flat non-lead, 32 terminals, no leads; 0.5 mm pitch, 5 mm x 5 mm x 0.9 mm body**

H-PQFN-32 I/O  
5 X 5 X 0.9 PKG, 0.5 PITCH

SOT617-29



RECOMMENDED STENCIL THICKNESS 0.125

## PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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**Figure 5. Reflow soldering footprint part 3 for H-PQFN32 (SOT617-29)**

H-PQFN32, thermal enhanced - plastic quad flat non-lead, 32 terminals, no leads; 0.5 mm pitch, 5 mm x 5 mm x 0.9 mm body

H-PQFN-32 I/O  
5 X 5 X 0.9 PKG, 0.5 PITCH

SOT617-29

- NOTES:
- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
  - 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
  - 3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
  - 4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
  - 5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.

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Figure 6. Package outline note H-PQFN32 (SOT617-29)

## 4 Legal information

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H-PQFN32, thermal enhanced - plastic quad flat non-lead, 32 terminals, no leads; 0.5 mm pitch, 5 mm x 5 mm x 0.9 mm body

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